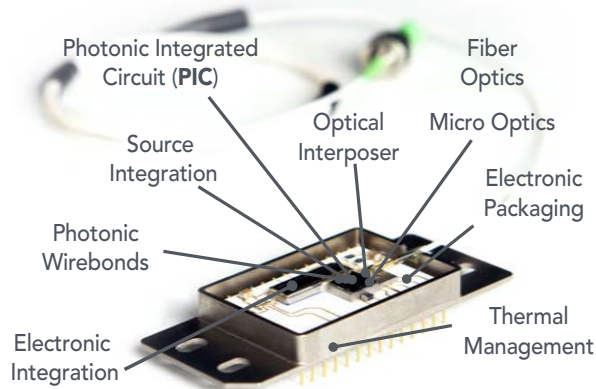
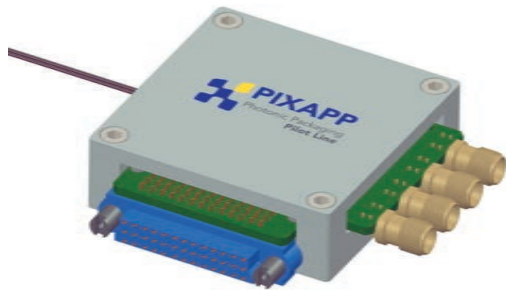


PIXAPP Packaging Technologies

PICs are complex multifunctional devices, so **PIXAPP** provides a full range of assembly and packaging technologies technologies.



PIXAPP's broad technology offering ensures that users have a single facility wherein they can find the technologies and expertise needed to support their full packaging requirements. **PIXAPP** has the capacity to manage multiple users simultaneously, ensuring fast process cycle-times and minimum delays between incoming user orders and delivery of packaged PICs.



www.PIXAPP.eu

PIXAPP Training & Education

Advanced PIC design, fabrication and packaging training programme, with access to state-of-the-art facilities and equipment, a comprehensive set of dedicated lectures and technology mentoring.

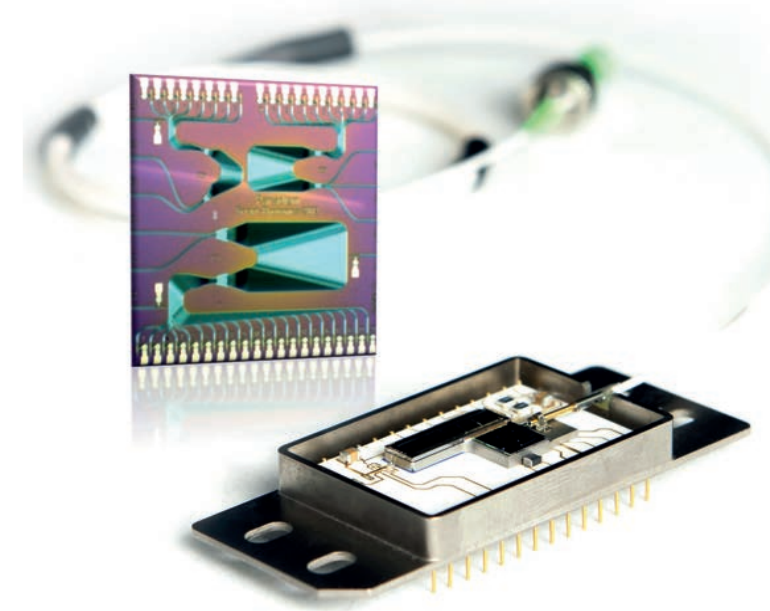


PIXAPP is an EC funded initiative, in a public-private partnership with Photonics21. **PIXAPP** is the world's first open-access Photonic Integrated Circuit (PIC) Assembly and Packaging Pilot line, and help users exploit the breakthrough advantages of PIC technologies.



PHOTONICS PUBLIC PRIVATE PARTNERSHIP

PIXAPP Photonic Packaging Pilot Line



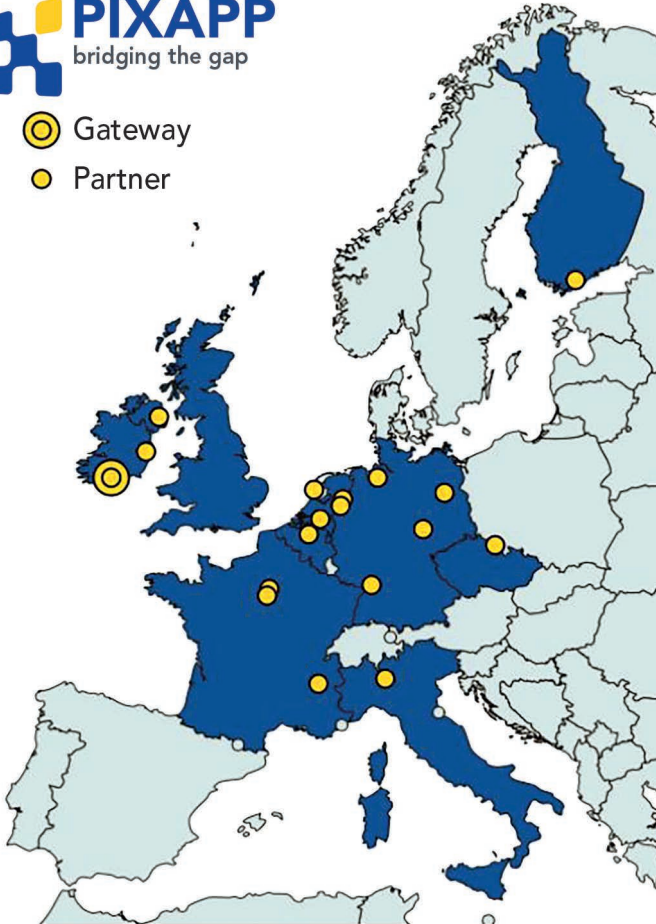
World's First Open-Access Photonic Integrated Circuit Assembly and Packaging Pilot Line

PIXAPP Partners

PIXAPP combine Europe's leading industrial & research packaging organisations, working together to offer users 'best-in-class' photonic packaging, assembly, and testing technologies.

PIXAPP bridging the gap

- ⊙ Gateway
- Partner



www.PIXAPP.eu

PIXAPP Easy User Access

PIXAPP is the world's first open-access Photonic Integrated Circuit (PIC) Assembly and Packaging Pilot line, and helps users exploit the breakthrough advantages of PIC technologies.

PIXAPP consists of a highly-interdisciplinary team of Europe's leading industrial & research organisations, and provides users with single-point access to PIC assembly and packaging.

The Pilot Line **Gateway Office** is PIXAPP's the easy-access interface for external users, and is located at the Tyndall National Institute, in Ireland. The Gateway is managed by an experienced team, including technical experts to review incoming user requests, and project managers to organise the PIXAPP supply chain.

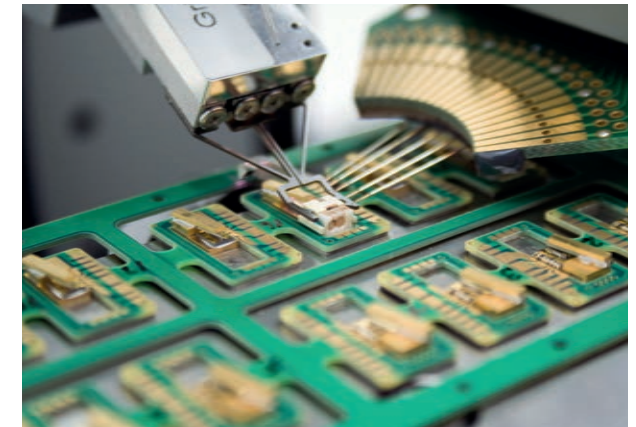
PIXAPP bridges the 'valley of death' often associated with moving from prototyping to low-volume fabrication, by giving companies an easy-access route to transferring R&D results to the market.

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PIXAPP Design to Manufacture



Comprehensive Packaging Design



Packaging Equipment & Testing



PHOTONICS²¹

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